PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Jungwon Suh	10/06/2009

RECEIVING PARTY DATA

Name:	QUALCOMM Incorporated
Street Address:	5775 Morehouse Drive
Internal Address:	Patent Department
City:	San Diego
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12574919

CH $40.00 12574919

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	091766
NAME OF SUBMITTER:	Sam Talpalatsky

Total Attachments: 2
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ASSIGNMENT

Vertically Stackable Dies Having Chip Identifier Structures

TO WHOM IT MAY CONCERN:

For the sum of One Dollar and other valuable consideration to us in hand paid, receipt of which is hereby acknowledged, be it known that I,

1. Jungwon Suh, a citizen of Korea, having a mailing address of 5775 Morehouse Drive, San Diego, CA 92121; and a resident of San Diego, California.

have sold, assigned and transferred and by these presents do sell, assign, transfer and set over unto QUALCOMM Incorporated, a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, its successors, legal representatives, or assigns, the entire right, title and interest in and to a certain invention relating to **Vertically Stackable Dies Having Chip Identifier Structures** by me devised and the application for United States Patent therefore filed in the United States Patent and Trademark Office on October 7, 2009, and assigned Serial No. 12/574,919, (and I hereby authorize and instruct **QUALCOMM Incorporated** to hereafter complete this Assignment by inserting the serial number and date in the space provided above when known), and all original and reissue patents granted thereof, and all divisions, continuations and continuations-in-part thereof, including the subject matter of any and all claims which may be obtained in every such patent, and all foreign rights to said invention, and covenant that I have full right to do so, and agree that I will communicate to said corporation or its representatives all facts known to me respecting said invention, whenever requested, and testify in any legal proceedings, sign all lawful papers, make all rightful oaths and generally do everything possible to aid said

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corporation, its successors, assigns and nominees, to obtain and enforce proper patent protection for said invention in all countries.

The Commissioner of Patents and Trademarks is requested to issue the Letters Patent which may be granted for said invention or any part thereof unto said corporation in keeping with this Assignment.

Done at San Diego, California this _6th_ day of __October_______, 2009.

/Jungwon Suh/
Jungwon Suh